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HOSTAFORM® SlideX® C0304 XAP®2
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POM copolymer Injection molding grade with tribological modification for demanding applications that require prevention of audible noise caused by stick-slip phenomenon. Excellent tribological performance with low friction and low wear under various conditions of sliding against plastics and metals. Reduced emission grade. Emissions according to VDA 275 < 5 mg/kg.

Chemical abbreviation according to ISO 1043-1: POM Molding compound ISO 29988-1: POM-K | M-GNRS2 | 5-2 | - | POM copolymer

Product information

Resin Identification	POM		ISO 1043
Part Marking Code	>POM<		ISO 11469

Rheological properties

Melt volume-flow rate	24	$cm^3/10min$	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.9	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2500	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	56	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	8	%	ISO 527-1/-2
Nominal strain at break	45	%	ISO 527-1/-2
Flexural modulus	2350	MPa	ISO 178
Flexural strength	77	MPa	ISO 178
Charpy impact strength, 23°C	150	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	145	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	5.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	5.5	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	132	MPa	ISO 2039-1
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	90	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	140	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	140	E-6/K	ISO 11359-1/-2

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1400	kg/m^3	ISO 1183

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Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	195	°C
Min. melt temperature	180	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	133	°C

Characteristics

Processing	Injection Moulding
Delivery form	Granules
Special characteristics	Low wear / Low friction, High Flow, Low emissions

Additional information

Injection molding

Processing

See Processing Guide and Involve Celanese FTS support to obtain best quality parts

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems

Storage

The product can then be stored in standard conditions until processed.

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Mercedes-Benz	DBL5404	BQF

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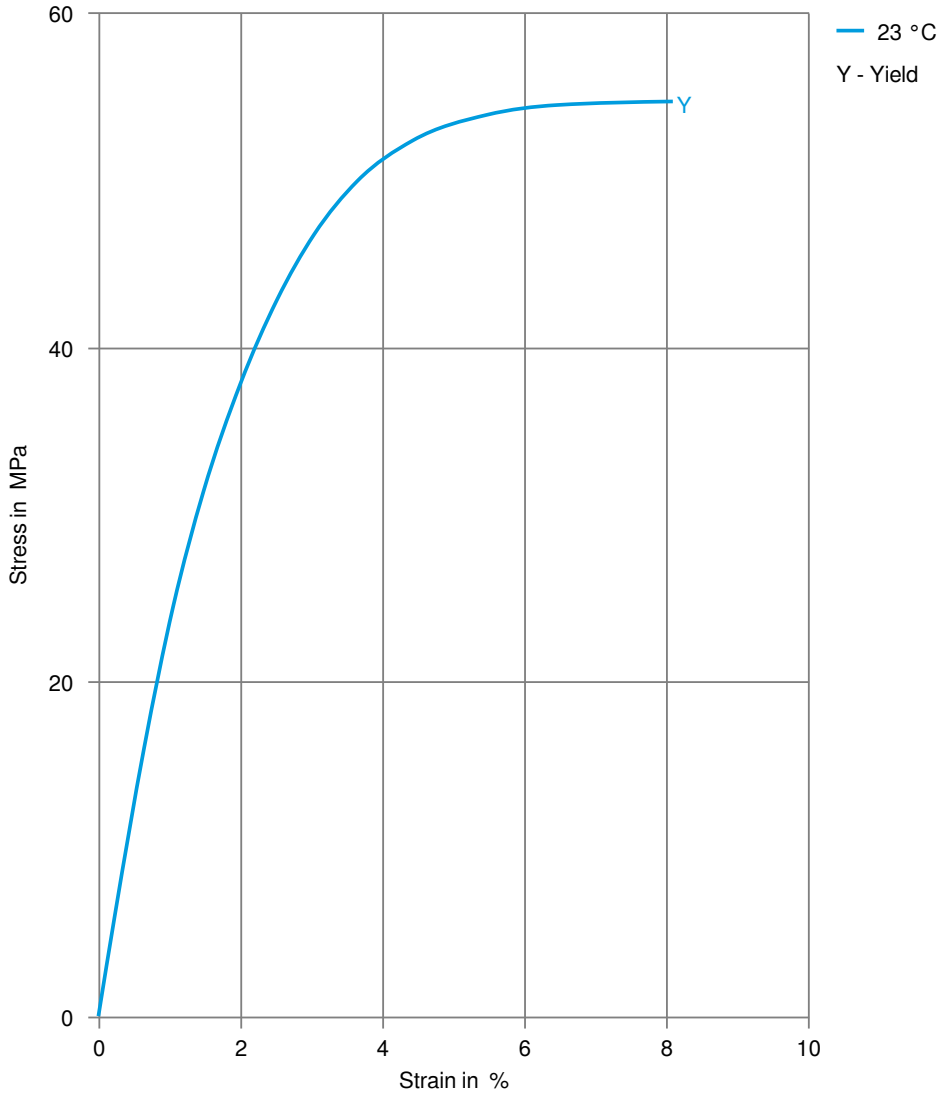
Stress-strain



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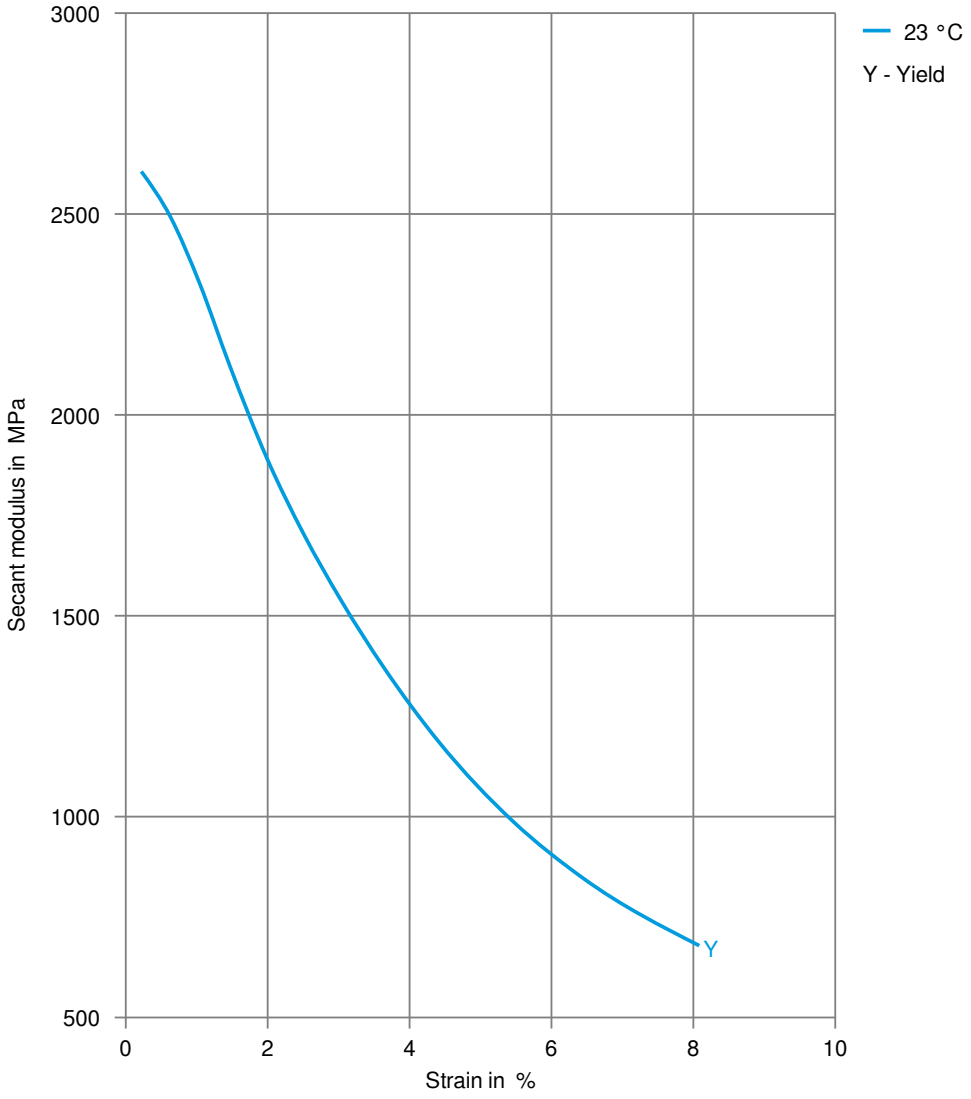
Secant modulus-strain



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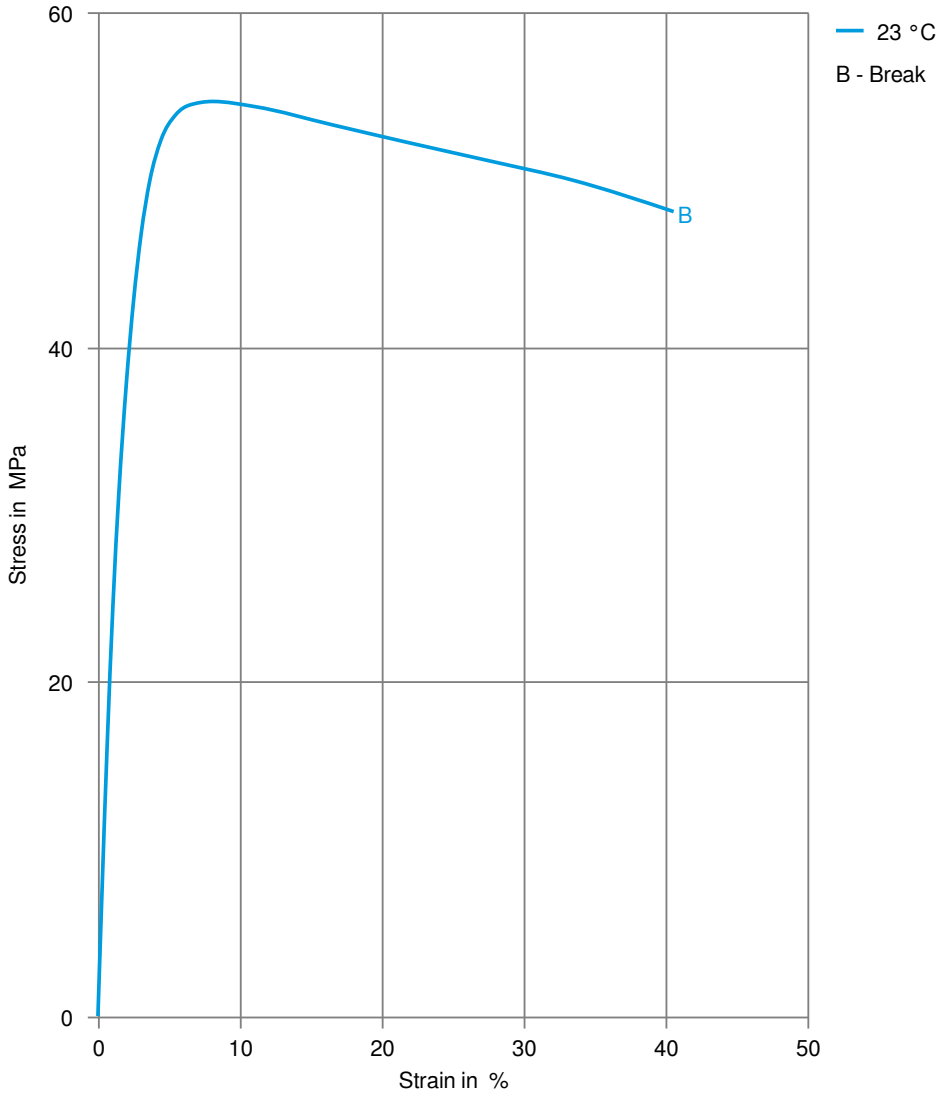
Stress-strain, 50mm/min



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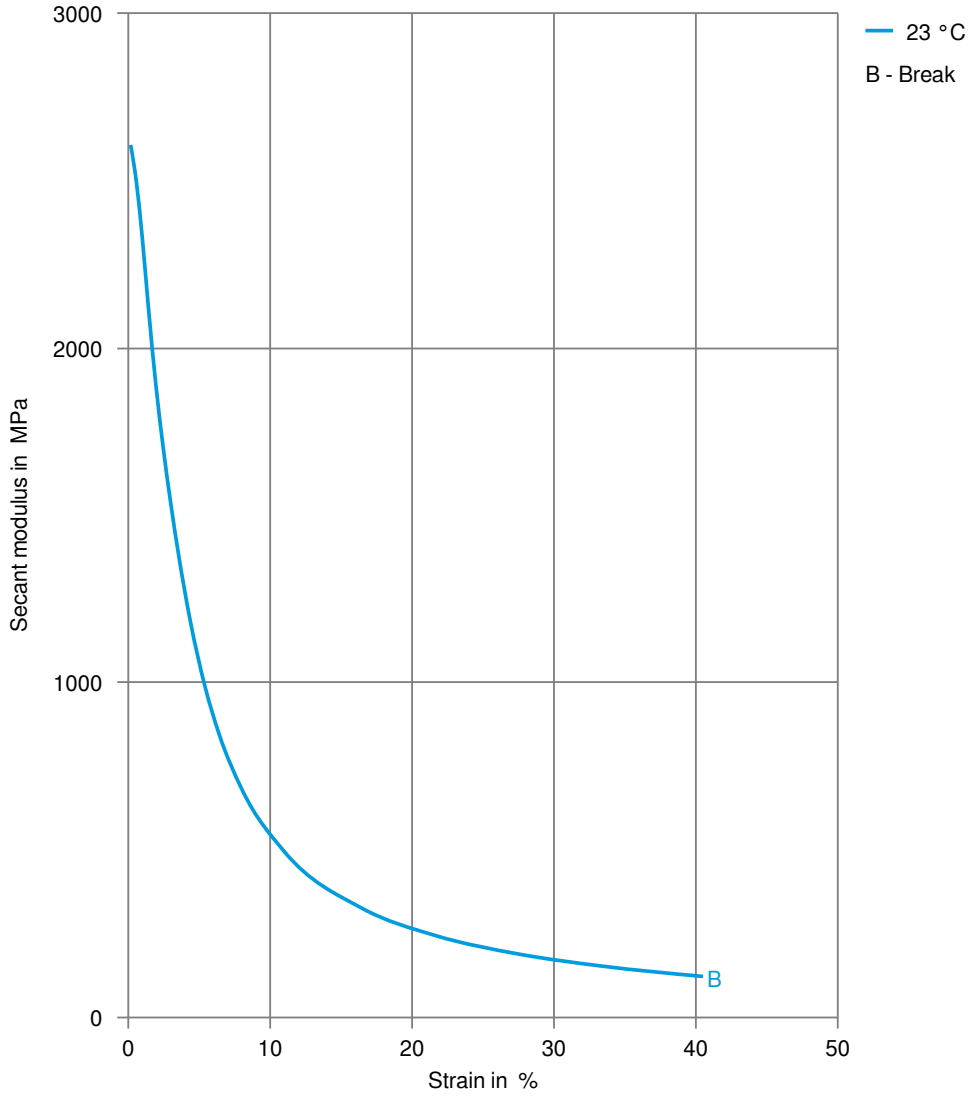
Secant modulus-strain, 50mm/min



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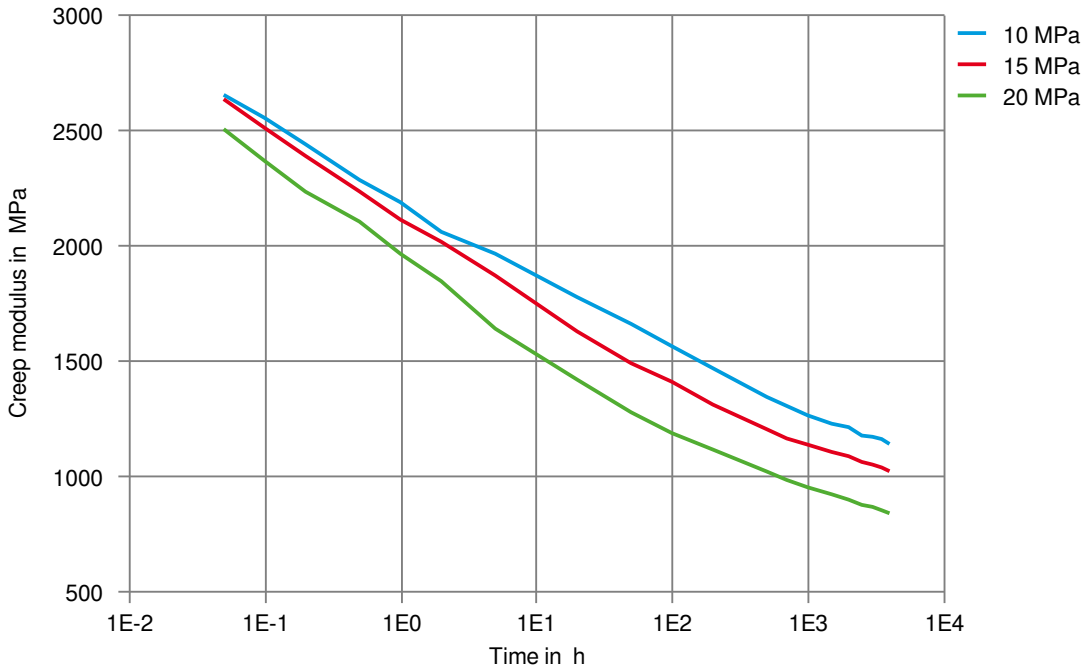
Creep modulus-time 23 °C



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Creep strain-time 23 °C